

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/05/2022

Details for "OPA734AIDBVT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
OPA734AIDBVT	NIPDAU	Level-2-260C-1 YEAR	Ext-Mfg	DBV   6	2.9x1.6x1.45	18.5

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Precious Metals	Gold	7440-57-5	0.038863	100	1000000	0.210166	2102
Sub-Total			0.038863	100	1000000	0.210166	2102
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.202513	80.000079	800001	1.095165	10952
Thermoplastics	Epoxy	85954-11-6	0.050628	19.999921	199999	0.27379	2738
Sub-Total			0.253141	100	1000000	1.368954	13690
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	5.943993	97.442492	974425	32.144362	321444
Copper and Its Alloys	Iron	7439-89-6	0.14335	2.35	23500	0.775219	7752
Copper and Its Alloys	Phosphorus	7723-14-0	0.005033	0.082508	825	0.027218	272
Zinc and Its Alloys	Zinc	7440-66-6	0.007625	0.125	1250	0.041235	412
Sub-Total			6.100001	100	1000000	32.988033	329880
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.09512	95.12	951200	0.514397	5144
Precious Metals	Gold	7440-57-5	0.00078	0.78	7800	0.004218	42
Precious Metals	Palladium	7440-05-3	0.0041	4.1	41000	0.022172	222
Sub-Total			0.1	100	1000000	0.540787	5408
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	9.847214	85.999999	860000	53.252487	532525
Other Plastics and Rubber	Carbon Black	1333-86-4	0.057251	0.499998	5000	0.309606	3096
Thermoplastics	Epoxy	85954-11-6	1.545784	13.500003	135000	8.359404	83594
Sub-Total			11.450249	100	1000000	61.921497	619215
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.549303	100	1000000	2.970561	29706
Sub-Total			0.549303	100	1000000	2.970561	29706
<b>Total</b>			18.491557			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/econfo](http://www.ti.com/econfo)  
 Created on: 06/05/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.